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March 2001 Revised January 2005

NC7WZ126

TinyLogic® UHS Dual Buffer with 3-STATE Outputs

General Description

The NC7WZ126 is a Dual Non-Inverting Buffer with independent active HIGH enables for the 3-STATE outputs. The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad $\rm V_{CC}$ operating range. The device is specified to operate over the 1.65V to 5.5V $\rm V_{CC}$ operating range. The inputs and outputs are high impedance when $\rm V_{CC}$ is 0V. Inputs tolerate voltages up to 5.5V independent of $\rm V_{CC}$ operating range. Outputs tolerate voltages above $\rm V_{CC}$ when in the 3-STATE condition.

Features

- Space saving US8 surface mount package
- MicroPak™ Pb-Free leadless package
- Ultra High Speed; t_{PD} 2.6 ns Typ into 50 pF at 5V V_{CC}
- High Output Drive; ±24 mA at 3V V_{CC}
- Broad V_{CC} Operating Range: 1.65V to 5.5V
- \blacksquare Matches the performance of LCX when operated at 3.3V V_{CC}
- Power down high impedance inputs/outputs
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Outputs are overvoltage tolerant in 3-STATE mode
- Patented noise/EMI reduction circuitry implemented

Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7WZ126K8X	MAB08A	WZ26	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3k Units on Tape and Reel
NC7WZ126L8X	MAC08A	T6	Pb-Free 8-Lead MicroPak, 1.6 mm Wide	5k Units on Tape and Reel

Pb-Free package per JEDEC J-STD-020B.

Logic Symbol



Pin Descriptions

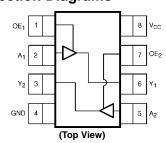
Pin Names	Description
OE _n	Enable Inputs for 3-STATE Outputs
A _n	Inputs
Y _n	3-STATE Outputs

Function Table

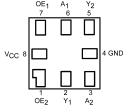
Inp	Inputs					
OE	OE A _n					
Н	L	L				
Н	Н	Н				
L	L	Z				
L	Н	Z				
H = HIGH Logic Level	L = LOW Logic Level	Z = 3-STATE				

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Connection Diagrams



Pad Assignments for MicroPak



(Top Thru View)

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Absolute Maximum Ratings(Note 1)

Supply Voltage (V _{CC})	-0.5V to $+7.0V$
DC Input Voltage (V _{IN}) (Note 2)	-0.5V to +7.0V
DC Output Voltage (V _{OUT})	-0.5V to +7.0V
DC Input Diode Current (I _{IK})	
@V _{IN} < 0V	−50 mA
DC Output Diode Current (I _{OK})	
@V _{OUT} < 0V	−50 mA
DC Output Source/Sink Current (I _{OUT})	±50 mA
DC V _{CC} /GND Current (I _{CC} /I _{GND})	±100 mA
Storage Temperature Range (T _{STG})	-65°C to $+150^{\circ}\text{C}$
Junction Temperature under Bias (T _J)	+150°C
Junction Lead Temperature (T _L)	
(Soldering, 10 seconds)	+260°C
Power Dissipation (P _D) @+85°C	250 mW

Recommended Operating Conditions (Note 3)

1.65V to 5.5V
1.5V to 5.5V
0V to 5.5V
0V to V_{CC}
0V to 5.5V
-40°C to $+85^{\circ}\text{C}$
0 ns/V to 20 ns/V
0 ns/V to 10 ns/V
0 ns/V to 5 ns/V
250°C/W

Note 1: Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. The datasheet specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside datasheet specifications.

Note 2: The input and output negative voltage ratings may be exceeded is the input and output diode current ratings are observed.

Note 3: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V _{CC}	$T_A = +25^{\circ}C$			T _A = -40°C to +85°C		Unit	Conditions	
Syllibol	Farameter	(V)	Min	Тур	Max	Min	Max	Onn	Conditions	
V _{IH}	HIGH Level Input Voltage	1.65 to 1.95	0.75 V _{CC}			0.75 V _{CC}		V		
		2.3 to 5.5	0.7 V _{CC}			0.7 V _{CC}		V		
V _{IL}	LOW Level Input Voltage	1.65 to 1.95			0.25 V _{CC}		0.25 V _{CC}	V		
		2.3 to 5.5			0.3 V _{CC}		0.3 V _{CC}	V		
V _{OH}	HIGH Level Output Voltage	1.65	1.55	1.65		1.55				
		2.3	2.2	2.3		2.2		V	$V_{IN} = V_{IH}$	$I_{OH} = -100 \ \mu A$
		3.0	2.9	3.0		2.9		V	or V _{IL}	
		4.5	4.4	4.5		4.4				
		1.65	1.29	1.52		1.29				$I_{OH} = -4 \text{ mA}$
		2.3	1.9	2.15		1.9			$V_{IN} = V_{IH}$	$I_{OH} = -8 \text{ mA}$
		3.0	2.4	2.80		2.4		V	or V _{IL}	$I_{OH} = -16 \text{ mA}$
		3.0	2.3	2.68		2.3				$I_{OH} = -24 \text{ mA}$
		4.5	3.8	4.20		3.8				$I_{OH} = -32 \text{ mA}$
V _{OL}	LOW Level Output Voltage	1.65		0.0	0.10		0.10			
		2.3		0.0	0.10		0.10	V	$V_{IN} = V_{IH}$	$I_{OL} = 100 \ \mu A$
		3.0		0.0	0.10		0.10	v	or V _{IL}	
		4.5		0.0	0.10		0.10			
		1.65		0.08	0.24		0.24			I _{OL} = 4 mA
		2.3		0.10	0.3		0.3		$V_{IN} = V_{IH}$	$I_{OL} = 8 \text{ mA}$
		3.0		0.15	0.4		0.4	V	or V _{IL}	$I_{OL} = 16 \text{ mA}$
		3.0		0.22	0.55		0.55			$I_{OL} = 24 \text{ mA}$
		4.5		0.22	0.55		0.55			$I_{OL} = 32 \text{ mA}$
I _{IN}	Input Leakage Current	0 to 5.5			±0.1		±1	μΑ	$V_{IN} = 5.5V$, GND
I _{OZ}	3-STATE Output Leakage	1.65 to 5.5			±0.5		±5	μΑ	$V_{IN} = V_{IH}$	or V _{IL}
									0 ≤ V _{OUT} :	≤ 5.5V
I _{OFF}	Power Off Leakage Current	0.0			1		10	μΑ	V _{IN} or V _{OI}	_{JT} = 5.5V
I _{CC}	Quiescent Supply Current	1.65 to 5.5			1		10	μΑ	$V_{IN} = 5.5V$, GND
	·	L	L			ı	L			-

Noise Characteristics

Symbol	Parameter	V_{CC} $T_A = +25^{\circ}C$		Units	Conditions	
	i didilicioi	(V)	Тур	Max	O.I.I.O	ooaliioiio
V _{OLP} (Note 4)	Quiet Output Maximum Dynamic V _{OL}	5.0		1.0	V	$C_L = 50 \text{ pF}$
V _{OLV} (Note 4)	Quiet Output Minimum Dynamic V _{OL}	5.0		1.0	V	$C_L = 50 \text{ pF}$
V _{OHV} (Note 4)	Quiet Output Minimum Dynamic V _{OH}	5.0		4.0	V	C _L = 50 pF
V _{IHD} (Note 4)	Minimum HIGH Level Dynamic Input Voltage	5.0		3.5	V	$C_L = 50 \text{ pF}$
V _{ILD} (Note 4)	Maximum LOW Level Dynamic Input Voltage	5.0		1.5	V	C _L = 50 pF

Note 4: Parameter guaranteed by design.

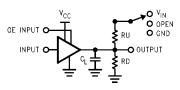
AC Electrical Characteristics

Symbol	Parameter	V _{CC}		T _A = +25°C	;	$T_A = -40^\circ$	C to +85°C	Units	Conditions	Figure	
Symbol	Parameter	(V)	Min Typ		Max	Max Min Max		Units	Conditions	Number	
t _{PLH}	Propagation Delay	1.8 ± 0.15	2.0		12.0	2.0	13.0		C _L = 15 pF		
t _{PHL}	A _n to Y _n	2.5 ± 0.2	1.0		7.5	1.0	8.0	ns	$RD=1\ M\Omega$	Figures	
		3.3 ± 0.3	0.8		5.2	0.8	5.5	ns	$S_1 = OPEN$	1, 3	
		5.0 ± 0.5	0.5		4.5	0.5	4.8	•			
t _{PLH}	Propagation Delay	3.3 ± 0.3	1.2		5.7	1.2	6.0		C _L = 50 pF		
t _{PHL}	A _n to Y _n	5.0 ± 0.5	0.8		5.0	0.8	5.3	ns	$RD=500\Omega$	Figures 1, 3	
									$S_1 = OPEN$.,,-	
toslh	Output to Output Skew	3.3 ± 0.3			1.0		1.0		C _L = 50 pF		
toshl	(Note 5)	5.0 ± 0.5			0.8		0.8	ns	$RD=500\Omega$	Figures 1, 3	
									S ₁ = OPEN		
t _{PZL}	Output Enable Time	1.8 ± 0.15	3.0		14.0	3.0	15.0		C _L = 50 pF		
t_{PZH}		2.5 ± 0.2	1.8		8.5	1.8	9.0	•	RD, RU = 500Ω		
		3.3 ± 0.3	1.2		6.2	1.2	6.5	ns	$S_1 = GND \text{ for } t_{PZH}$	Figures 1, 3	
		5.0 ± 0.5	0.8		5.5	0.8	5.8	•	$S_1 = V_I \text{ for } t_{PZL}$., -	
									$V_I = 2 \times V_{\text{CC}}$		
t _{PLZ}	Output Disable Time	1.8 ± 0.15	2.5		12.0	2.5	13.0		C _L = 50 pF		
t _{PHZ}		2.5 ± 0.2	1.5		8.0	1.5	8.5	•	RD, RU = 500Ω		
		3.3 ± 0.3	0.8		5.7	0.8	6.0	ns	$S_1 = GND \text{ for } t_{PHZ}$	Figures 1, 3	
		5.0 ± 0.5	0.3		4.7	0.3	5.0	•	$S_1 = V_I \text{ for } t_{PLZ}$., 0	
									$V_I = 2 \times V_{CC}$		
C _{IN}	Input Capacitance	0		2.5				pF			
C _{OUT}	Output Capacitance	5.0		4				þΓ			
C _{PD}	Power Dissipation	3.3		10				pF	(Note 6)	Figure 2	
	Capacitance	5.0		12				μ	(14016-0)	Figure 2	

Note 5: Parameter guaranteed by design. to_SLH = | tp_LHmax - tp_LHmin |; to_SHL = | tp_HLmax - tp_HLmin |.

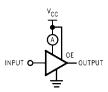
Note 6: C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2.) C_{PD} is related to I_{CCD} dynamic operating current by the expression:
I_{CCD} = (CPD) (V_{CC}) (f_{IN}) + (I_{CC} static).

AC Loading and Waveforms



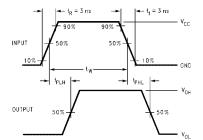
 ${
m C_L}$ includes load and stray capacitance Input PRR = 1.0 MHz, ${
m t_W}$ = 500 ns

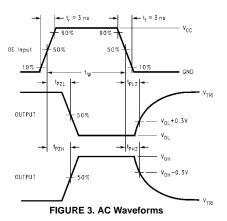
FIGURE 1. AC Test Circuit



 $\begin{aligned} & \text{Input} = \text{AC Waveform; } t_{\text{r}} = t_{\text{f}} = 1.8 \text{ ns;} \\ & \text{PRR} = 10 \text{ MHz; } \text{Duty Cycle} = 50\% \end{aligned}$

FIGURE 2. I_{CCD} Test Circuit



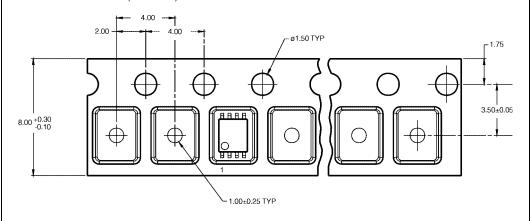


Tape and Reel Specification

TAPE FORMAT for US8

Package	Package Tape		Cavity	Cover Tape
Designator	Section	Cavities	Status	Status
	Leader (Start End)	125 (typ)	Empty	Sealed
K8X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

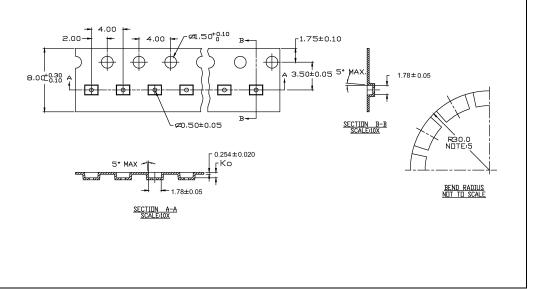
TAPE DIMENSIONS inches (millimeters)



TAPE FORMAT for MicroPak

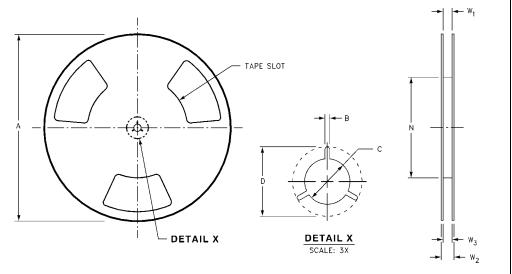
Package	Tape	Number	Cavity	Cover Tape	
Designator	Section	Cavities	Status	Status	
	Leader (Start End)	125 (typ)	Empty	Sealed	
L8X	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (typ)	Empty	Sealed	

TAPE DIMENSIONS inches (millimeters)



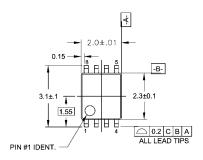
Tape and Reel Specification (Continued)

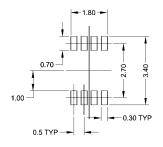
REEL DIMENSIONS inches (millimeters)



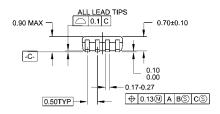
Tape Size	Α	В	С	D	N	W1	W2	W3
0	7.0	0.059	0.512	0.795	2.165	0.331 + 0.059/-0.000	0.567	W1 + 0.078/-0.039
8 mm	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.40 + 1.50/-0.00)	(14.40)	(W1 + 2.00/-1.00)

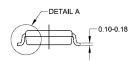
Physical Dimensions inches (millimeters) unless otherwise noted

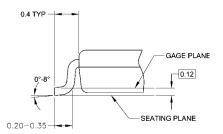




LAND PATTERN RECOMMENDATION







NOTES:

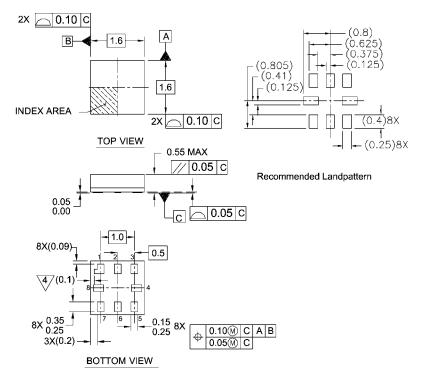
- CONFORMS TO JEDEC REGISTRATION MO-187
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

DETAIL A

MAB08AREVC

8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide Package Number MAB08A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Notes:

- 1. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y.14M-1994

4/PIN 1 FLAG, END OF PACKAGE OFFSET.

MAC08AREVC

Pb-Free 8-Lead MicroPak, 1.6 mm Wide Package Number MAC08A

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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